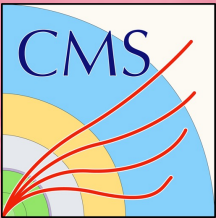


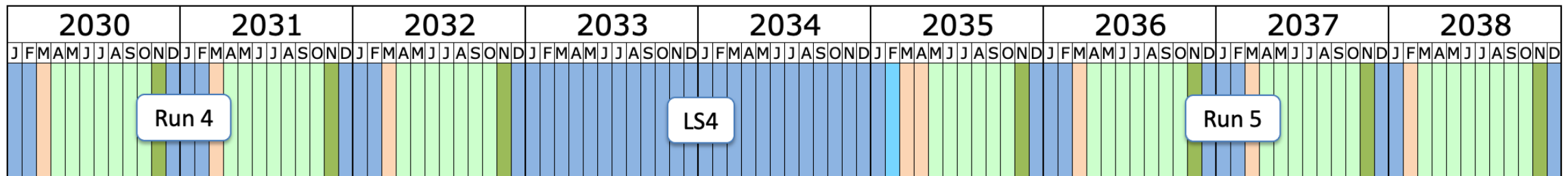
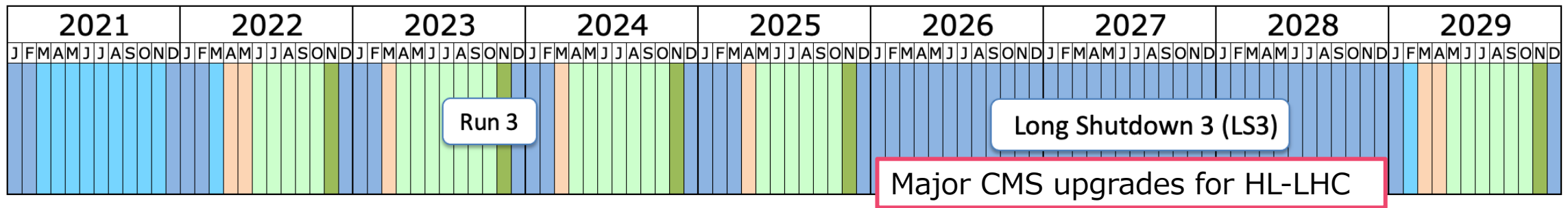
CMS High Granularity Calorimeter – Modules & Assembly

Dimitra Tsionou

HEP 2023, Ioannina



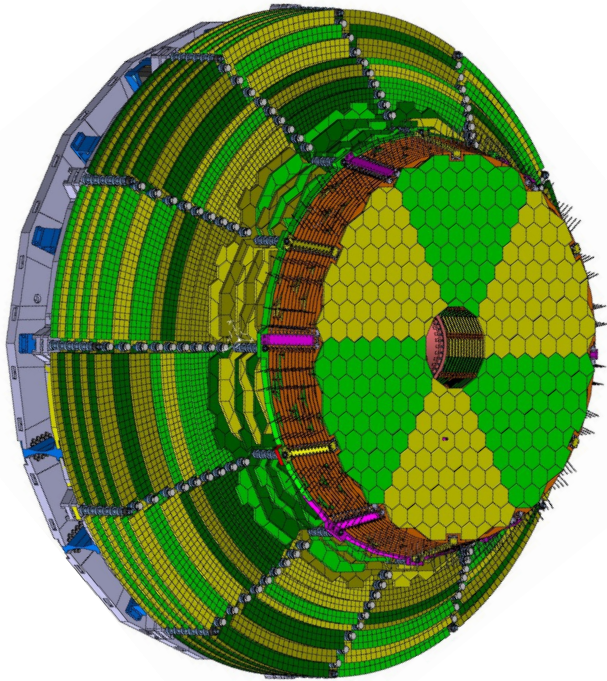
Why HGICAL



	LHC (now)	HL-LHC
Inst. Luminosity	$2 \times 10^{34} \text{ s}^{-1} \text{ cm}^{-2}$	$5-7.5 \times 10^{34} \text{ s}^{-1} \text{ cm}^{-2}$
Pileup events	O(40)	O(140-200)
Int. Luminosity	300 fb^{-1} (Run 3)	3000 fb^{-1}

- More radiation, more pile-up, higher track density, more data ,... → Detector Upgrades

HGCAL Overview



- CMS is constructing a High Granularity Calorimeter for the HL-LHC
- It will be composed of different technologies: Si sensors, SiPM-on-tile
- HGCAL characteristics
 - $1.5 < |\eta| < 3.0$
 - High granularity
 - Radiation tolerant
 - Precise hit/cluster timing
 - Particle flow
 - Operation at -30 C

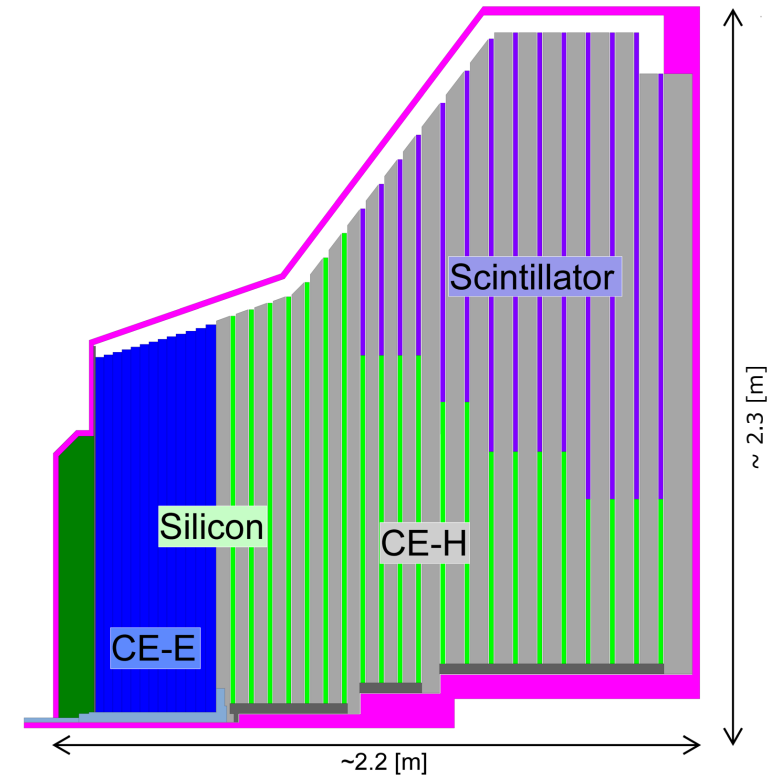
HGCAL Design

Active Elements

- Hexagonal modules based on Si sensors in EM part (CE-E) and high radiation regions of the hadronic part (CE-H)
- Scintillating tile with on-tile SiPM readout in low radiation regions of CE-H
- Cassettes → multiple modules mounted on cooling plates with electronics and absorbers

Parameters

- $\sim 620 \text{ m}^2$ Si sensors in $\sim 26\text{K}$ modules
 - 6M Si channels, cell size ~ 0.5 or $\sim 1 \text{ cm}^2$
 - $\sim 400 \text{ m}^2$ scintillators in $\sim 4\text{K}$ boards
 - 240K sci channels, cell size 4-30 cm^2
-
- EM calo (CE-E): Si, Cu/CuW/Pb absorbers, 26 layers, $27.7 X_0$
 - Hadronic Calo (CE-H): Si/scintillator, steel absorber, 21 layers, 8.5λ



Particle Flow

- Particle Flow Algorithms → make best use of all detectors to measure jet energy

"Typical" jet content:

62% charged particles (mainly hadrons)

27% photons

10% neutral hadrons

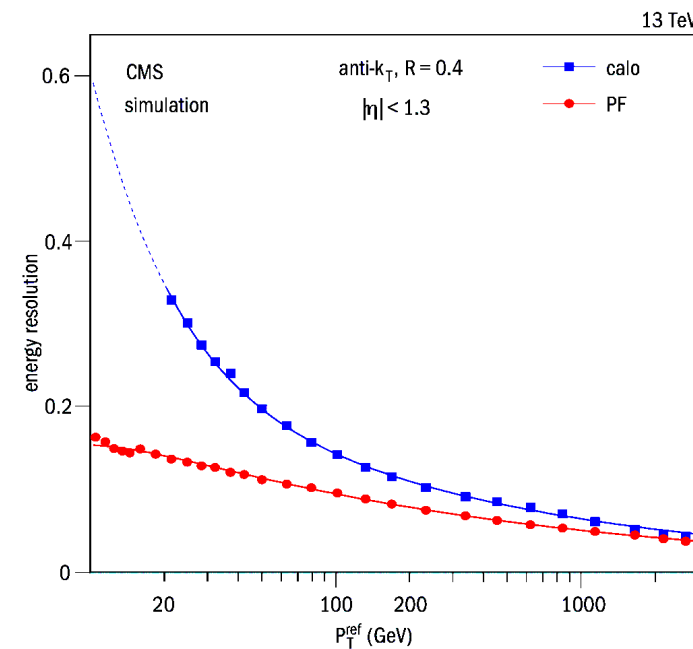
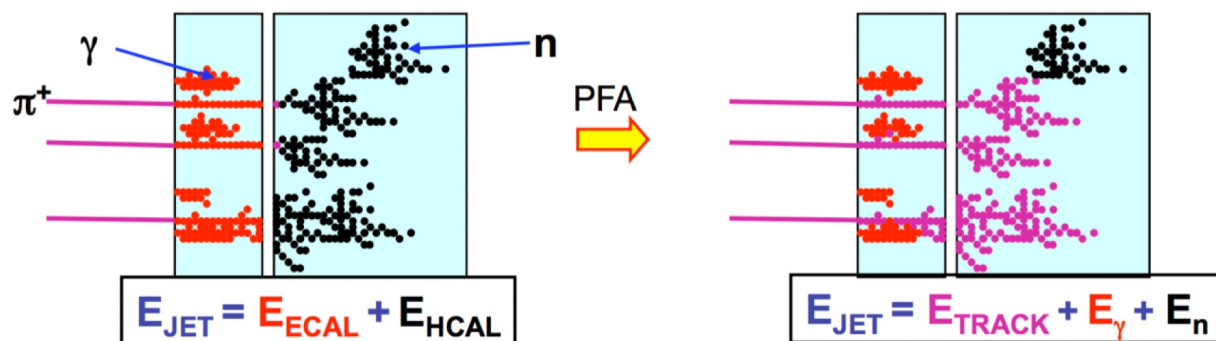
1% neutrinos

→ Tracker

→ ECAL

→ HCAL

X

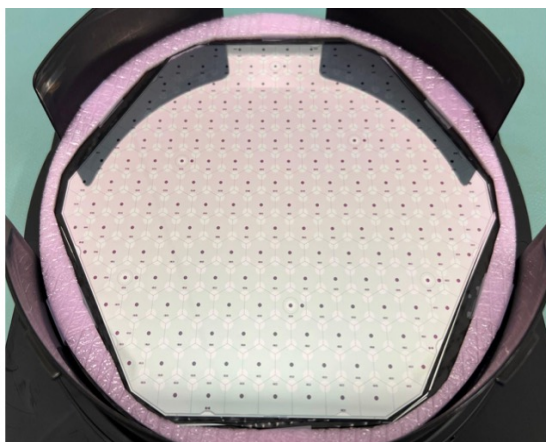


Better performance for **PF** compared to **calo** only

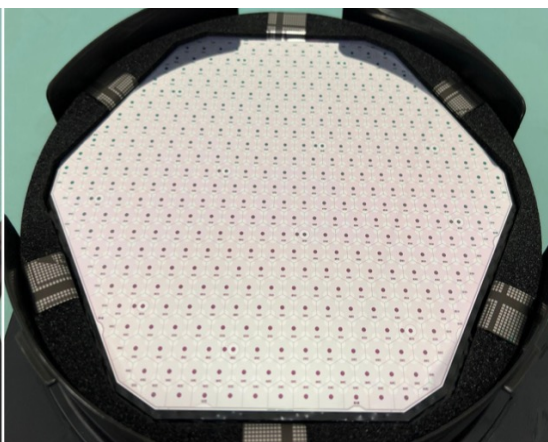
- Requires a highly granular calorimeter

Si sensors

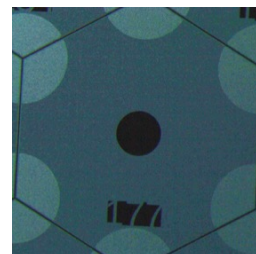
- 8" wafer
- Hexagonal shape (and partials)
- Low and high density varieties (depending on where they are placed)
- 120, 200 or 300 μm sensors (depending on where they are placed)



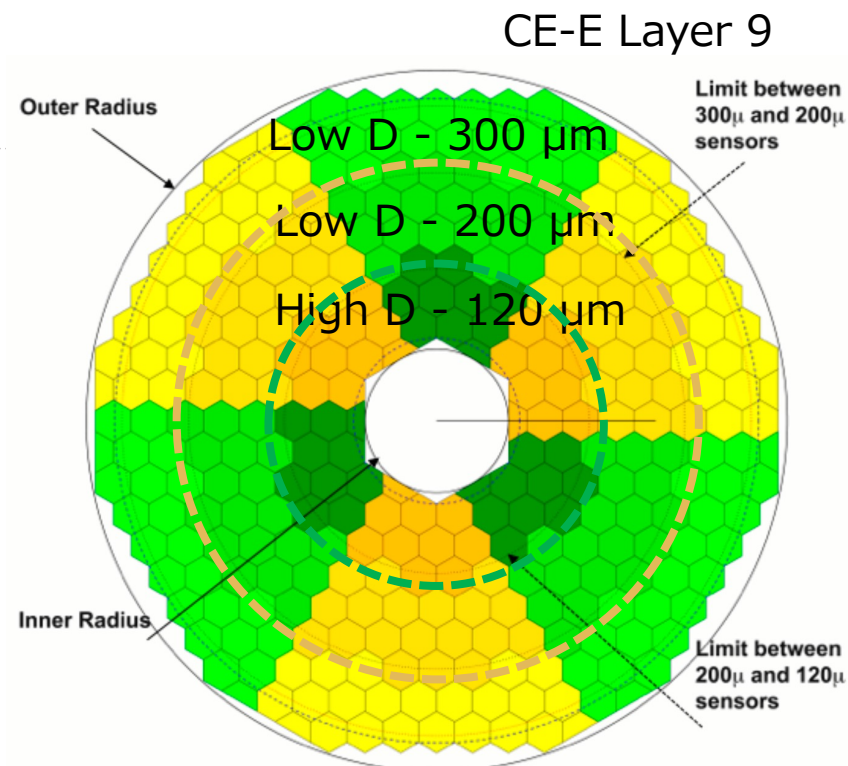
Low density sensor
~200 cells of 1 cm² size
200 or 300 μm thick



High density sensor
~400 cells of 0.5 cm² size
120 μm thick



Different partial
shapes for coverage

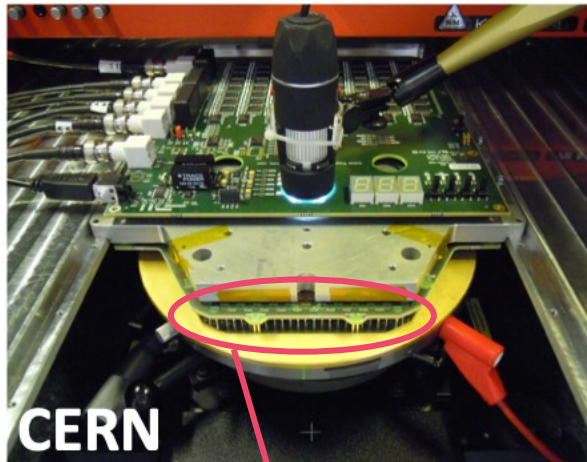


Close to the beam

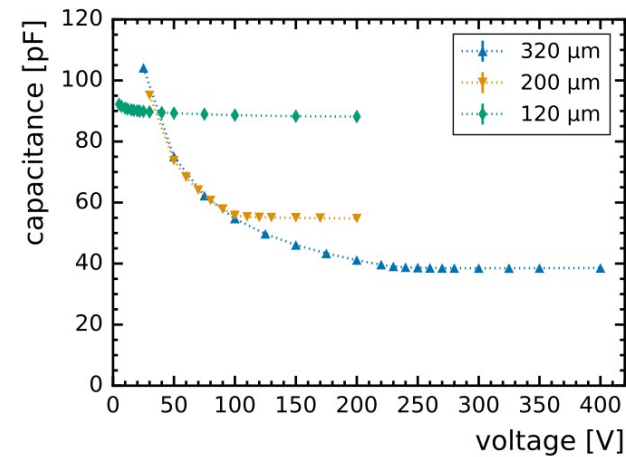
- High radiation \rightarrow thin sensors
- Higher track density \rightarrow higher density sensor pads

Si Sensors Testing

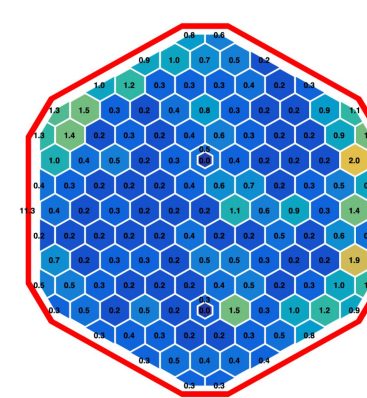
Setup



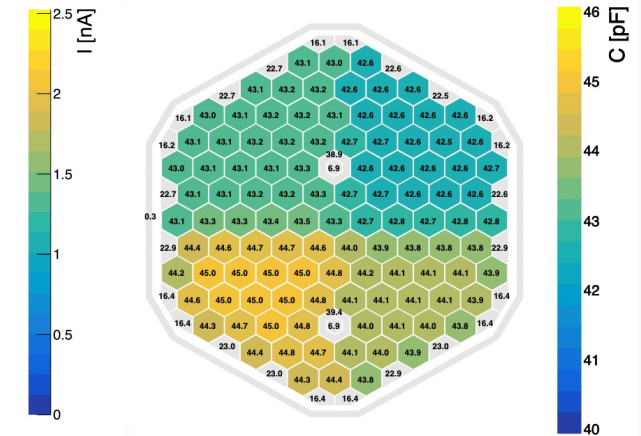
CV curves for sensors with different active thickness



Leakage current at 1000V

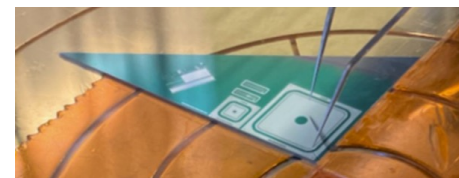
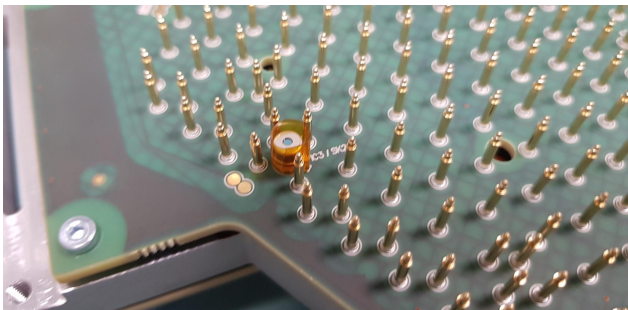


Capacitance at 400 V



4 quadrants because of four different cell geometries on the sensor (varying inter-pad gap)

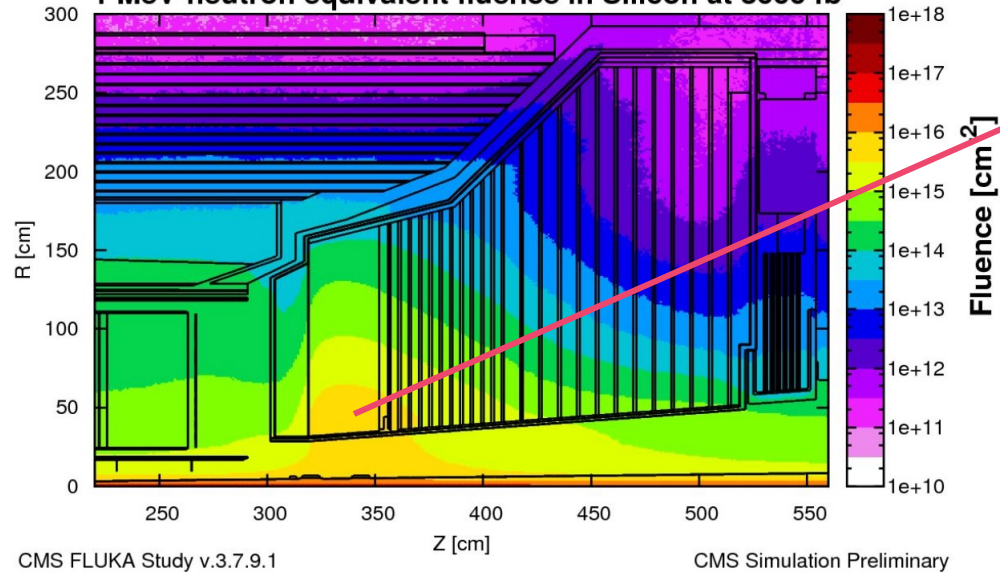
Test structures



Si Sensor Radiation Hardness

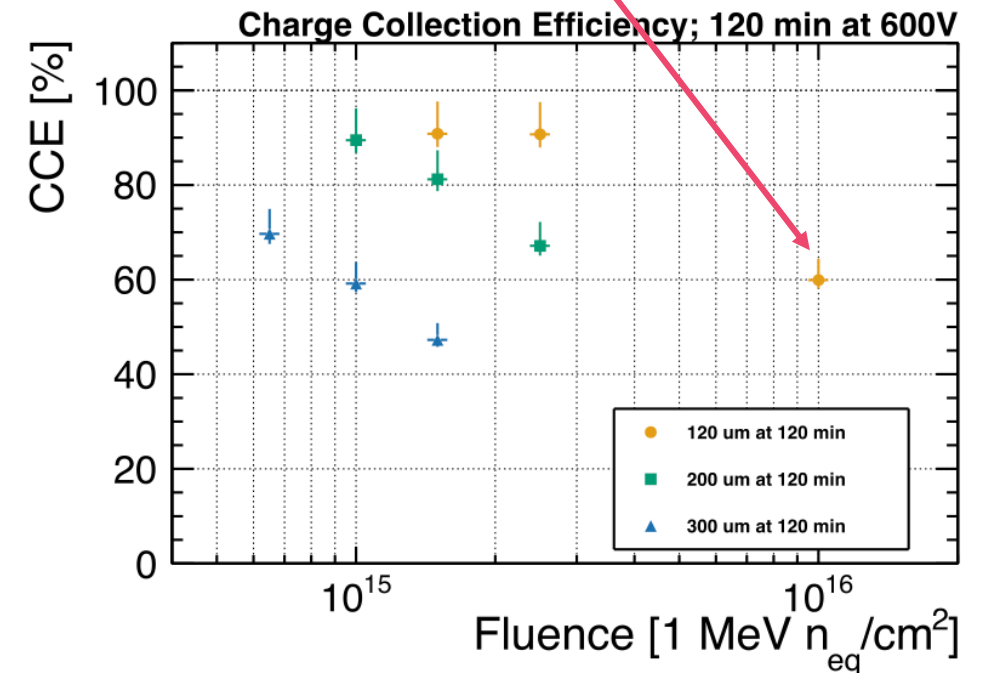
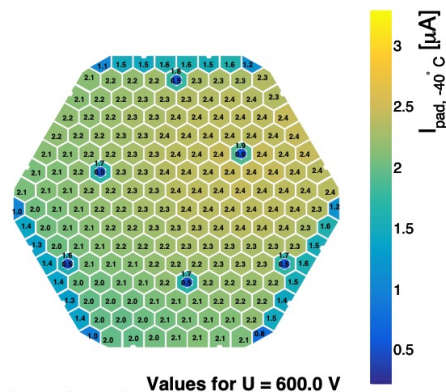
CMS p-p collisions at 7 TeV per beam

1 MeV-neutron equivalent fluence in Silicon at 3000 fb⁻¹

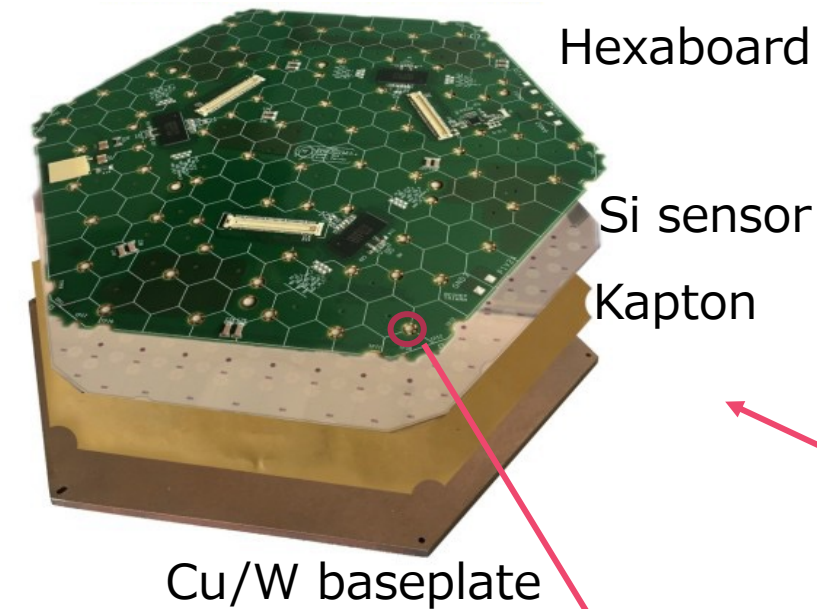


Area close to beam to be equipped with 120 μm sensors

Per-pad leakage current for sensor (after annealing):
200 μm, low density,
irradiated to 1.9×10^{15} neq/cm²



Si Modules



PCB ('Hexaboard') – Sensor

- Read-out (HGCROC) of sensor cells + bias supply
- Connects to motherboard for data transfer

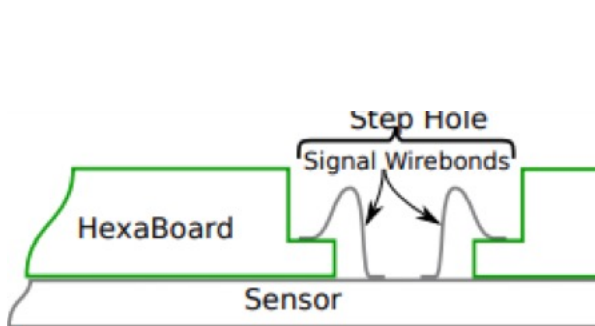
Silicon sensor

Kapton sheet

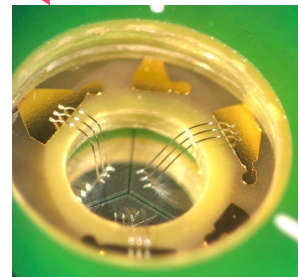
- Isolation to baseplate + bias supply to sensor back side

Baseplate

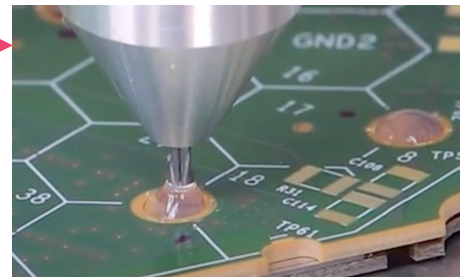
- Rigidity, contributes to absorber material



Step holes for wire bonding

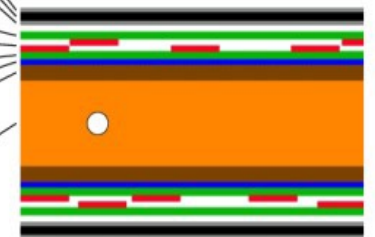


Encapsulation



Stainless-steel clad
Pb absorber
Stainless-steel clad

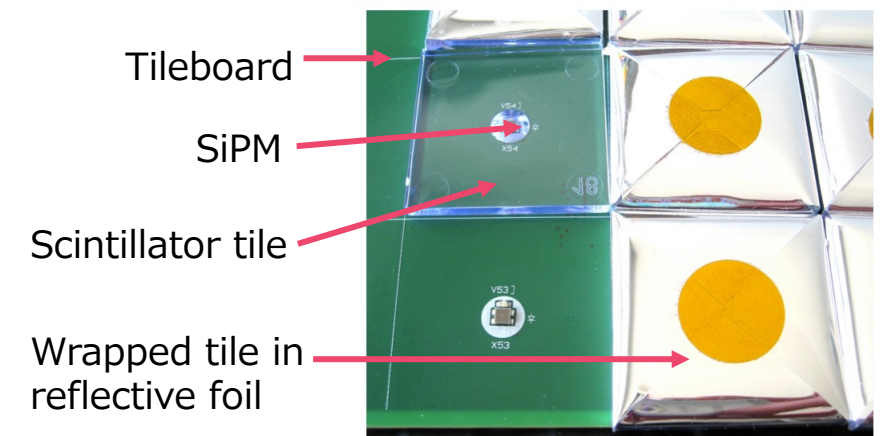
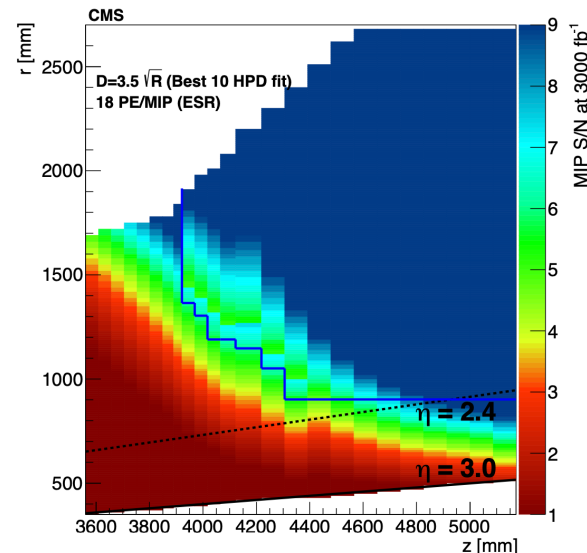
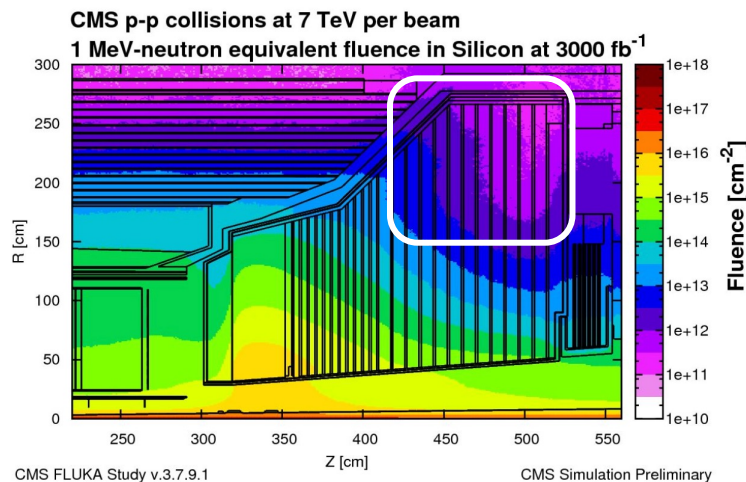
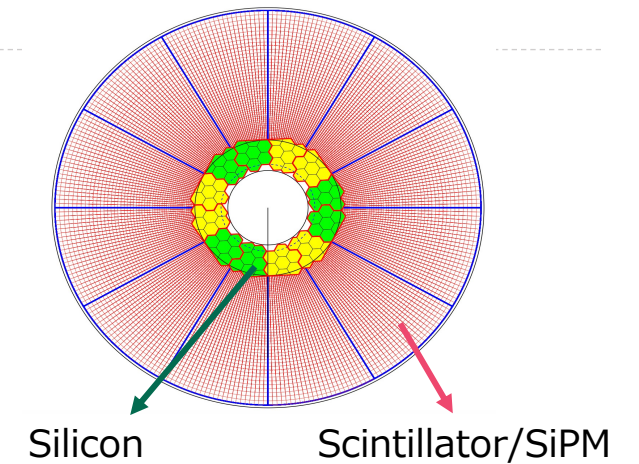
PCB motherboard
ASICs etc.
PCB sensor board
Silicon
CuW baseplate
Cu cooling plate



SiPM-on-Tile modules

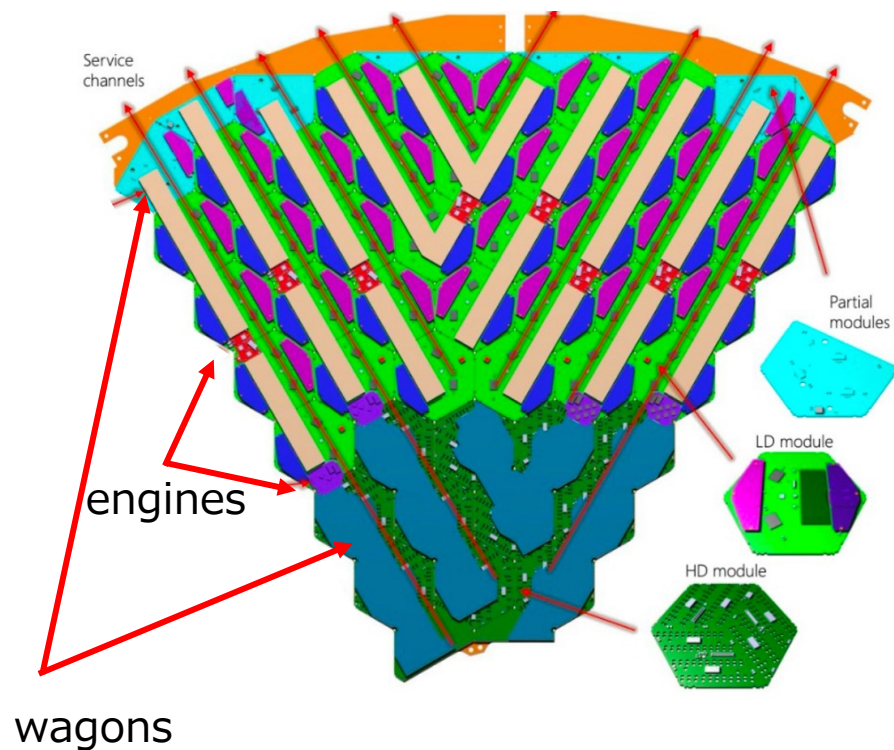
- SiPM-on-Tile: individually wrapped plastic scintillator tiles placed on silicon photomultipliers
- Scintillator tiles with SiPM readout used in low radiation regions
- Require good MIP Signal/Noise after 3000fb^{-1}
- Tile size depends on radial-position (4cm^2 to 32cm^2) \rightarrow smaller tiles at lower radii

CE-H mixed cassette

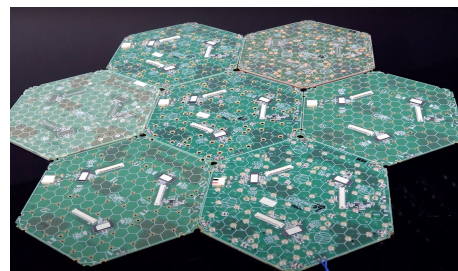


Cassettes

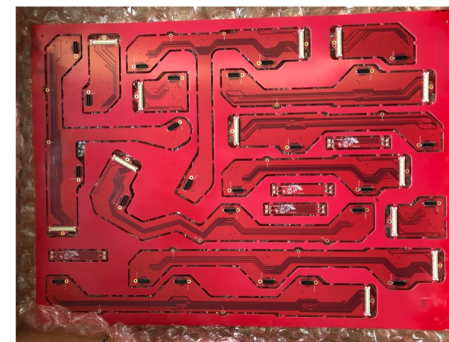
Full Si cassette (~400 components)



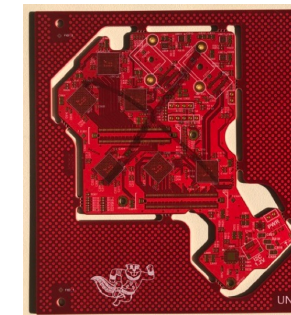
How to get there?



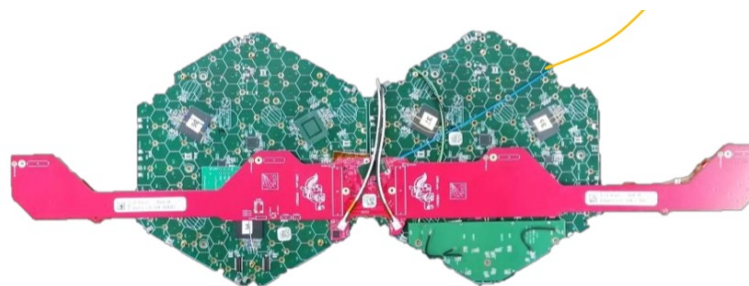
Hexagonal tiling



Wagons in different shapes. Connections from modules to engines



Engine boards collect data from wagons and send it to backend



Tests from 1-module to 2 → (multi) → trains → cassettes

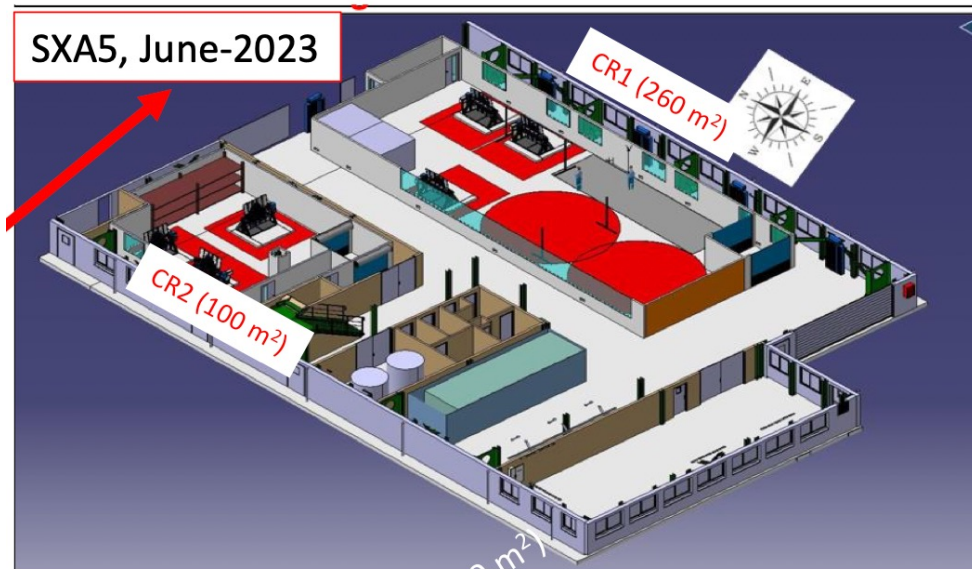
Slow control, fast control, data acquisition, testbeams, ...

Cassette Assembly

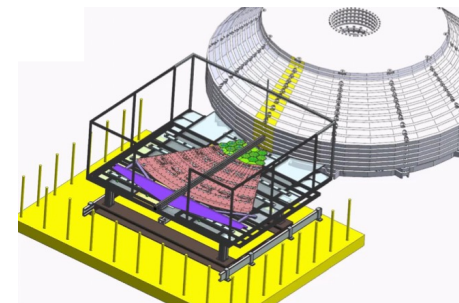
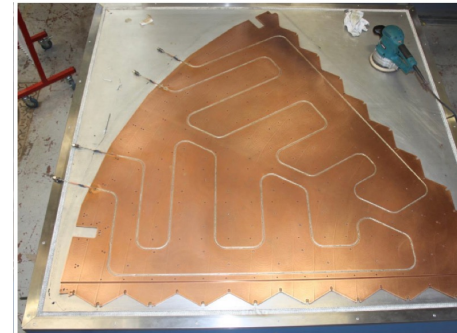
Assembly centers: CERN, Fermilab

~700 cassettes

CERN p5, under construction

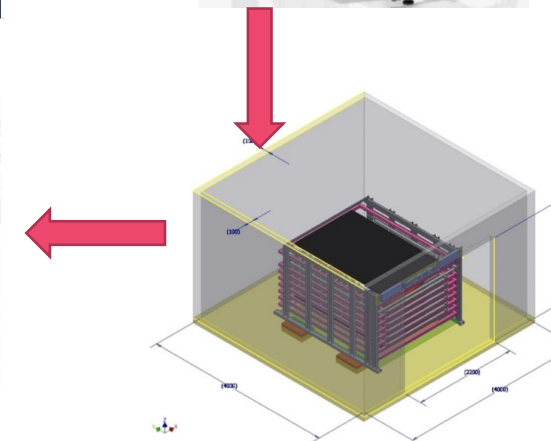
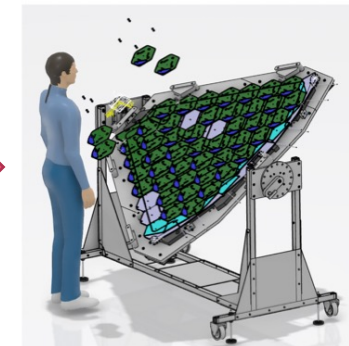


Cooling plate
CO₂ flow, -35 C
Few mm diameter
Few meters length



Insertion into
absorber

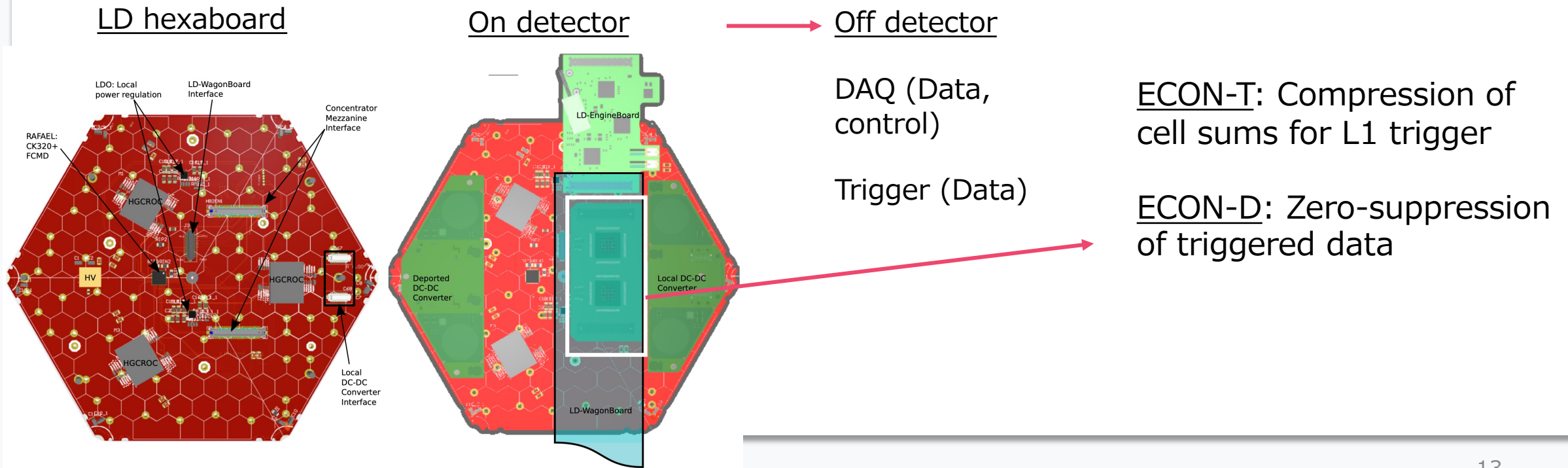
Moved to assembly
station



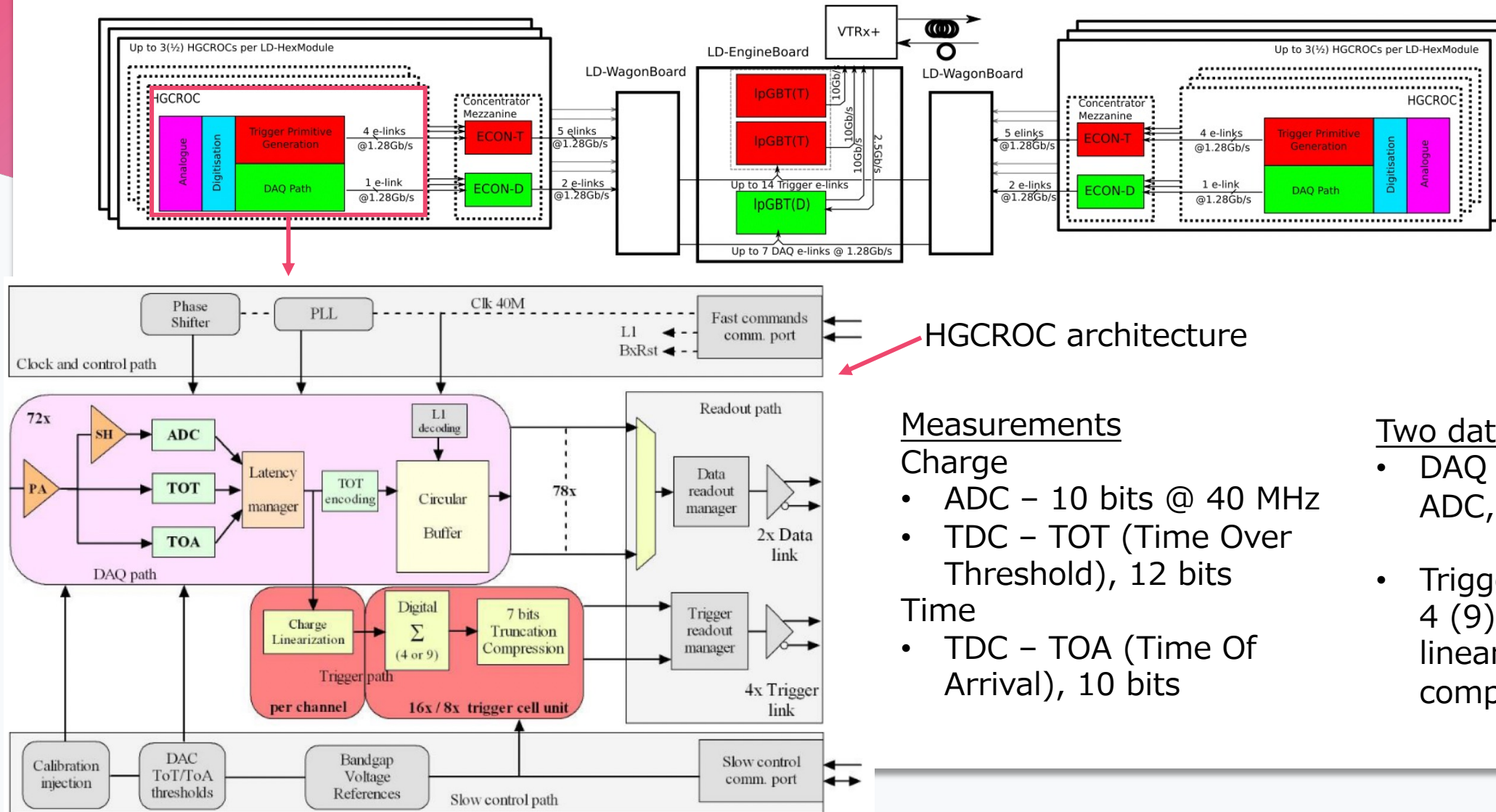
Move to cosmic stack

Electronics

- Different boards for the electronics
- Hexaboard for module → Different variants for HD/LD modules and partials
- HGCROC → ASIC used both for Si and SiPM-on-tile parts
- Requirements: high dynamic range (0.2 fC-10 pC), timing info (30ps), radiation tolerant, low power (<20mW per channel)



Front End Electronics & HGCROC



HGCROC architecture

Measurements

Charge

- ADC – 10 bits @ 40 MHz
- TDC – TOT (Time Over Threshold), 12 bits

Time

- TDC – TOA (Time Of Arrival), 10 bits

Two data flows

- DAQ path: Store ADC, TOT, TOA data
- Trigger path: Sum of 4 (9) channels, linearisation, compression

Beam Tests

- Test beams during the past few years
- 2018: test beam at CERN. Positrons / pions 20-300 GeV, muons 200 GeV
- 2 planned at CERN for 2023

CE-E

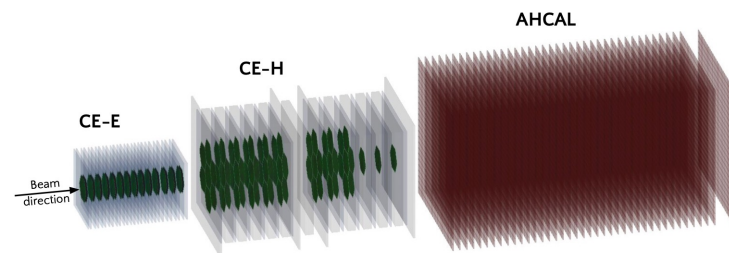
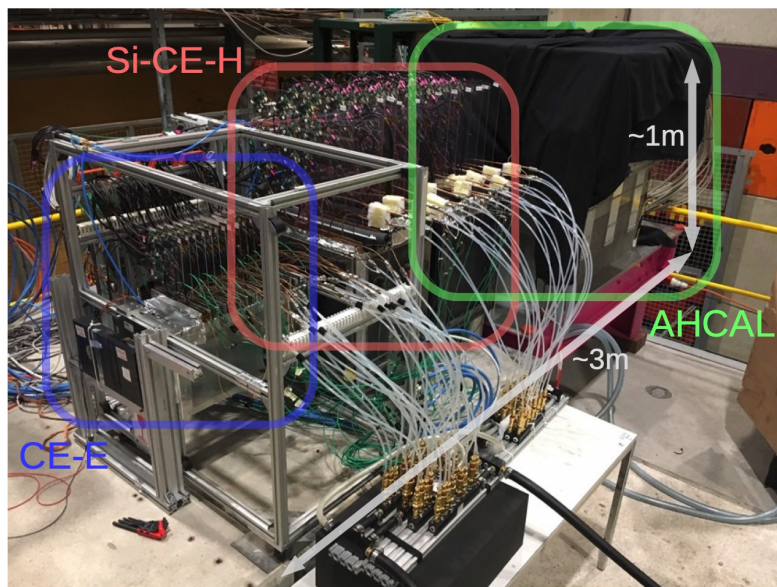
- 28 layers of single Si modules
- $\sim 26 X_0$

CE-H

- 9 layers of 7 Si modules + 3 layers of single Si modules
- $\sim 3.4 \lambda$

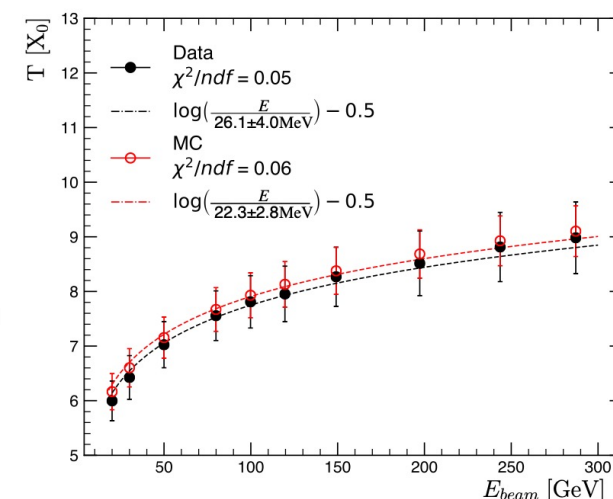
AHCAL

- 39 layers of SiPM-on-tile modules
- 22K scintillator tiles of size $3 \times 3 \times 0.3 \text{ cm}^3$
- $\sim 4.4 \lambda$

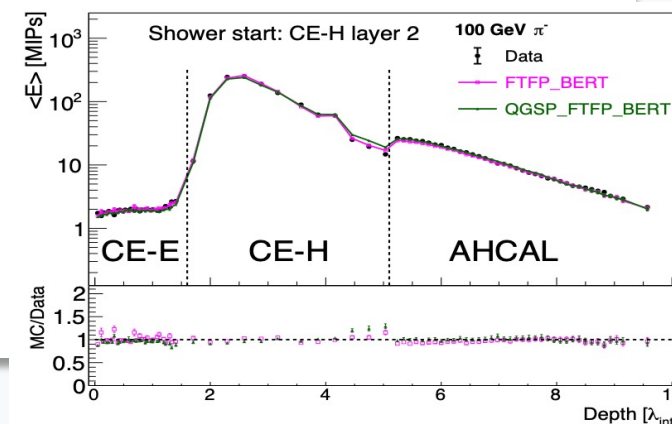


Longitudinal information

positron beam Shower max

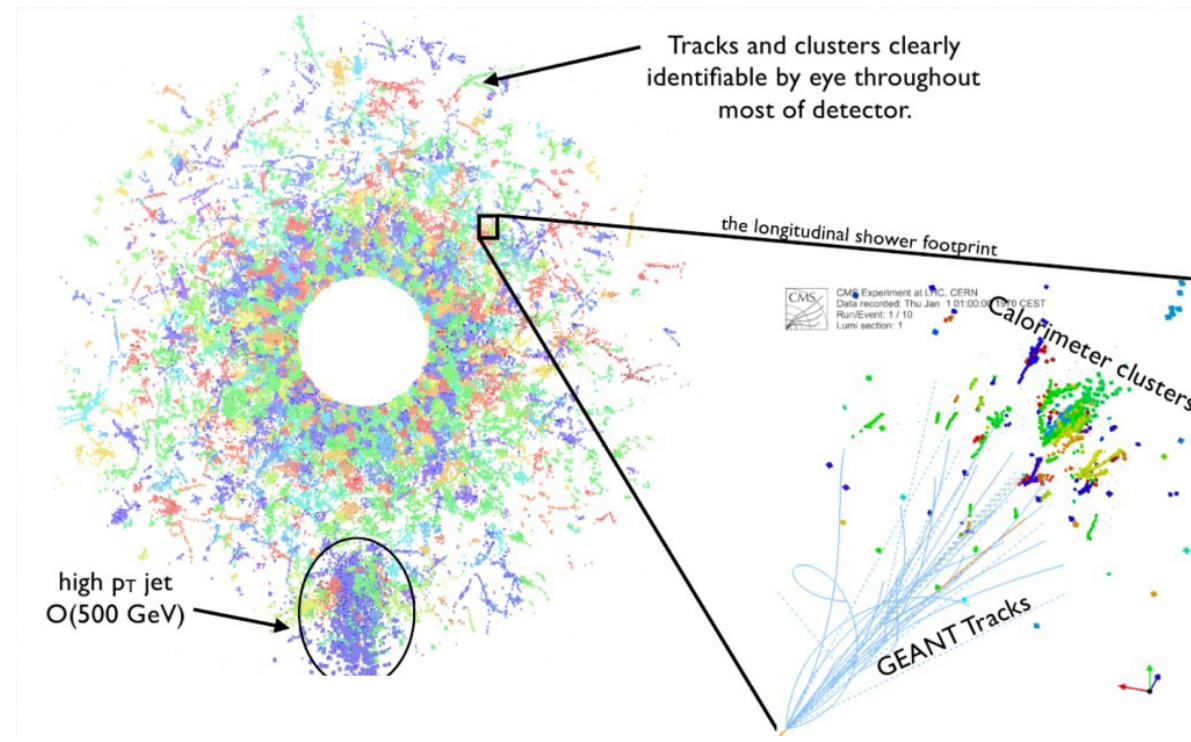


pion beam

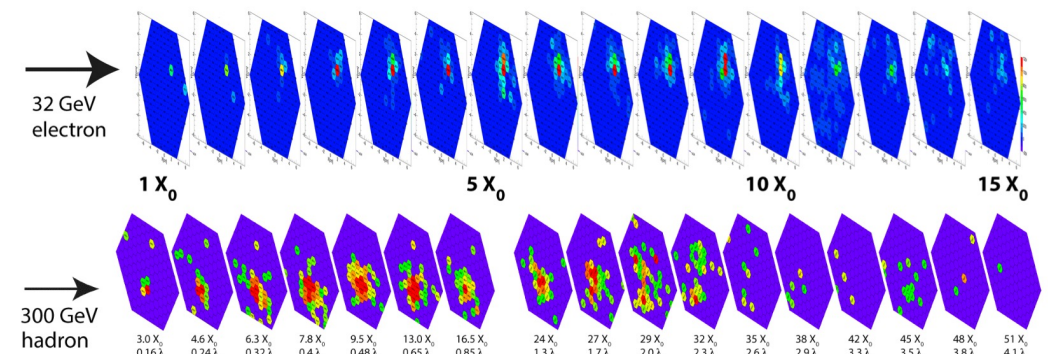


Reconstruction

- High Granularity Calorimeter → small cell size, 26 EM + 21 Had layers
- Can use modern computing technologies and reconstruction algorithms
- GPUs can be used
- Machine learning for particle ID
- CLUE, CLUE3D, TICL and others explored



Development of EM (top) and had (bottom) shower in different test beams (FNAL, CERN)

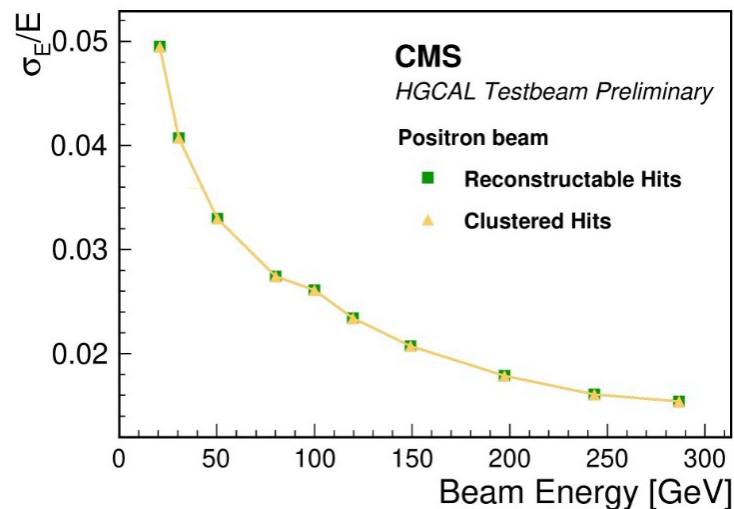


Reconstruction – Clustering Options

- Large number of recorded hits ($\sim 10^5$ per event) \rightarrow reduce info by building clusters

CLUE: algorithm for energy clustering:

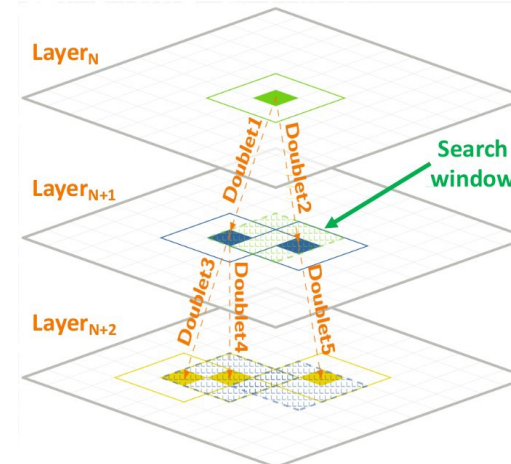
- Reduces the number of hit objects by building clusters of energy
 - Calculates energy density in a distance, defines seed/followers/outliers
- Can be parallelized and runs on GPUs
- Has been tested with testbeam data



TICL: The Iterative Clustering

- Particles deposit energy and create 'Rechits'
- Rechits are clustered together to form 2D LayerClusters (CLUE algorithm)
- Clusters on different layers are linked together to form Tracksters (showers)

Iterative approach: Reconstruct simpler objects first \rightarrow Mask reconstructed objects \rightarrow Reconstruct more complex objects in following iterations

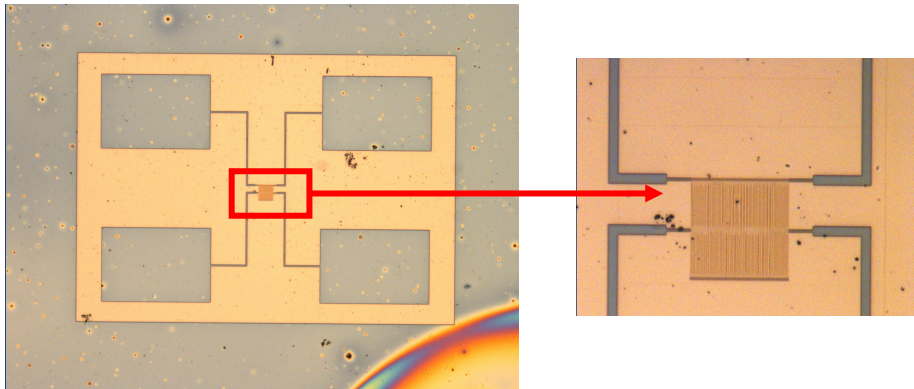


Trackster connecting several 2D LayerClusters

Other activities at NTU/TIDC

- Taiwan Instrumentation and Detector Consortium (TIDC)
- → Hardware for HGCal, sPHENIX, STAR, AnaBHEL,...

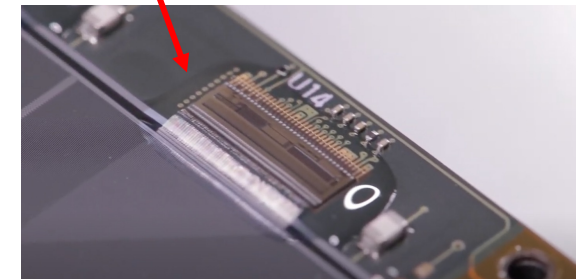
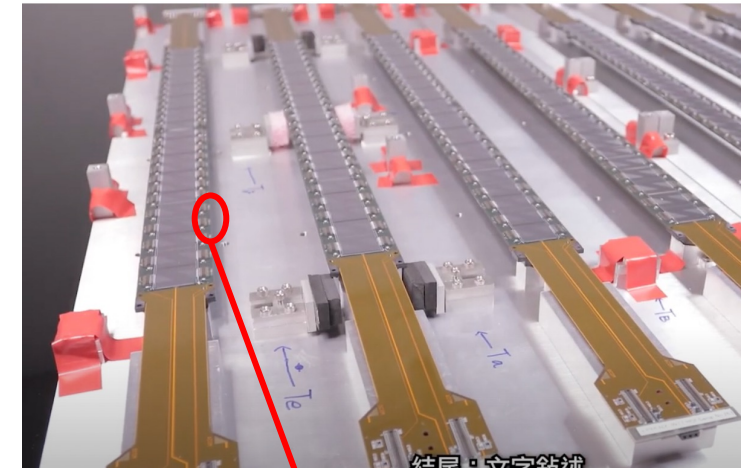
**Superconducting Nanowire
Single Photon Detectors:
SNSPDs**
In-house manufacturing!



STAR
Forward Silicon Tracker



sPHENIX Silicon Strip Tracker



Summary

- High Granularity Calorimeter upgrade for CMS HL-LHC
- → Si & SiPM-on-tile
- High precision → energy, spatial, timing
- Sensors will start arriving soon
- Electronics close-to-final
- Module pre-series production to start soon
- Cassette pre-series production to start later in 2023
- Validation of parts and procedures → All sorts of tests to come! (module, cassette, testbeams)
- Exciting times ahead!
- Talk on CMS upgrades by J. Virdee tomorrow

